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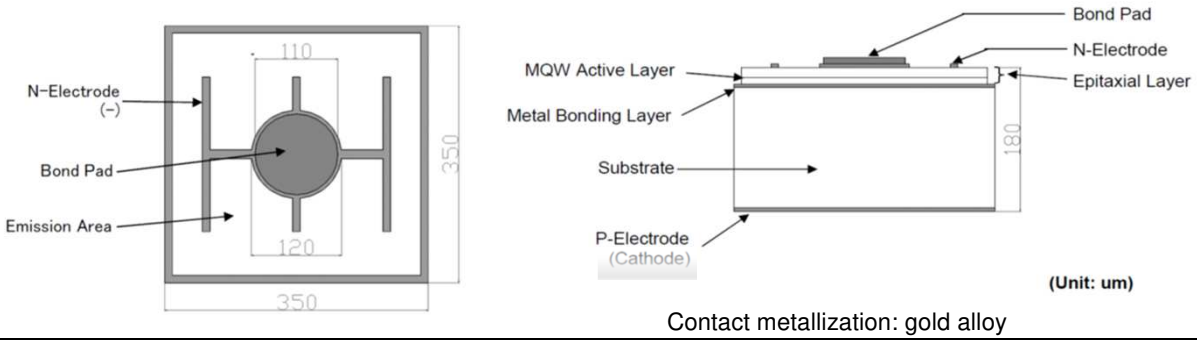
Data Sheet — Preliminary

LED Chip Infrared — EOLC-1550-27

Rev. 02, 2018

Radiation	Type	Electrodes
Infrared	MQW	n (cathode) up



Contact metallization: gold alloy

Die size (typ.): 0.350 mm × 0.350 mm (14 mil)
Thickness (typ.): 0.180 mm (7 mil)
Bond pad size: Ø 0.110 mm (periphery = Ø 0.120 mm)

Optical and Electrical Characteristics

T_{amb}= 25°C, unless otherwise specified

Parameter	Test cond.	Symbol	Min	Typ	Max	Unit
Forward voltage	I_F=20 mA	V_F		0.9		V
Radiant power*	I_F=20 mA	Φ_e		2.9		mW
Peak wavelength	I_F=20 mA	λ_p		1550		nm
FWHM	I_F=20 mA	$\Delta\lambda_{0.5}$		109		nm
Forward voltage	I_F=50 mA	V_F		0.96		V
Radiant power*	I_F=50 mA	Φ_e		5.1		mW
Forward voltage	I_F=100 mA	V_F		1.05		V
Radiant power*	I_F=100 mA	Φ_e		6.8		mW

*Measured on bare chip on TO-18 header

Packing

Dice on adhesive film with wire bond side up.

RoHS COMPLIANT Pb-Free

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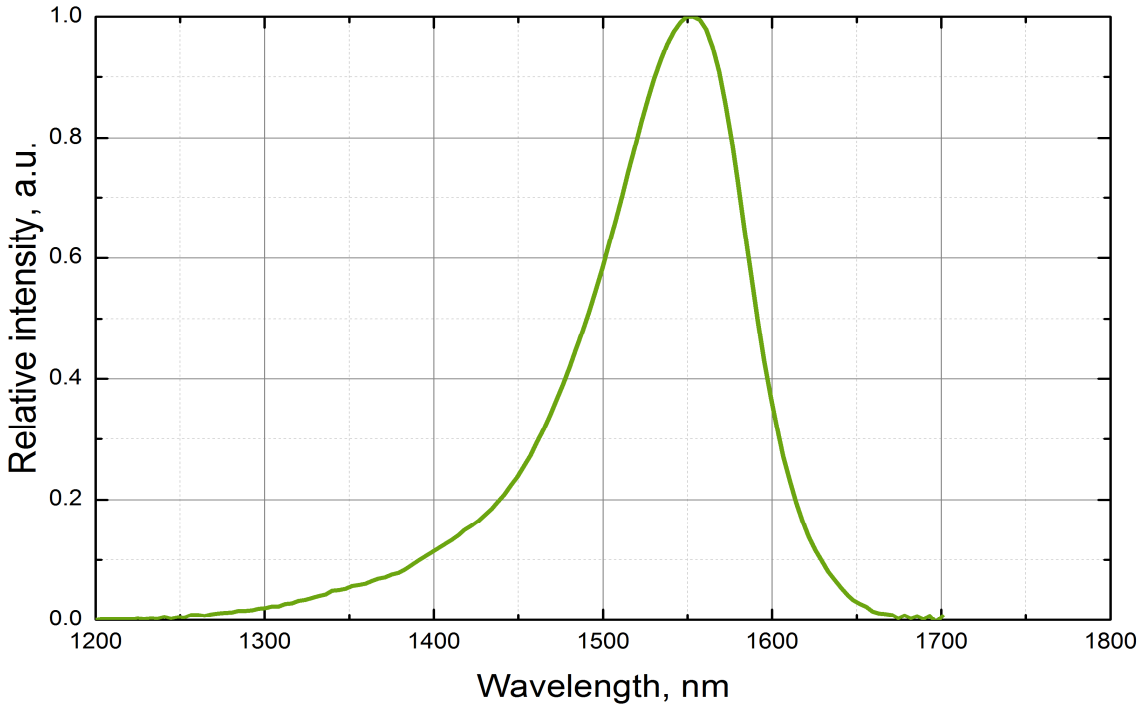

Spectrum at 20 mA

Art. No. 131 163

RoHS COMPLIANT Pb Pb-Free